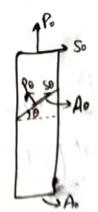


Metallwig The science and technology of metals and alloys - Physical metallurgy, mechanical metallurgy, process metallurgy, etc. Physical Metallurgy: with the physical and mechanical properties of metals as affected by composition, processing and environmental Mechanical Metallurgy: The science that studies the response of metals to applied forces. Buccess Metallurgy: Processing of fires to metals. - Materials, Science: Study of the properties of solid materials and how those proporties are determined by material's composition and structure, both macroscopic and microscopic. in 10,000 second 1000 8 100 8 1-10 =e same storain Strain rate & Resistance (Hardness) to deformation 17-05-2023 # Poughness: Energy ductility (or) toughness required (withsand) Resistance prior to failure FCC (Englured) bulk Toughness Toughness deformation \$ (BCC)→9400 → Most materials with FCC structure dudile ove used for 8ub-zero applications which do not have sharp de DBIT. Temperature (Dudie to Bruttle) Transition Temp. Depends on crystal structure, alloying chemical composition, etc.



Po: Applied load, so: shear force at basal plane

$$\sigma_{o} = \frac{\log d}{\operatorname{avea}} = \frac{s_{o}}{A} = 0$$
 $T = \frac{shear \log d}{\operatorname{avea}}$ $\sigma_{o} = \frac{l_{o}}{A_{o}}$

Find To, To, 60, Zo.

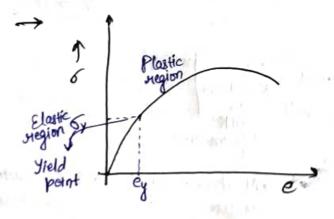
Somi So= Basino O.

$$\delta_{\theta} = \frac{P_0 \cos \theta}{A_0 / \cos \theta} = \delta_0 \cos^2 \theta$$

 $P_0 = P_0 = 0.80$ $S_0 = P_0 = 0.81$

$$A_{\theta} = \frac{A}{\cos \theta}$$

Shear stores I responsible for deformation



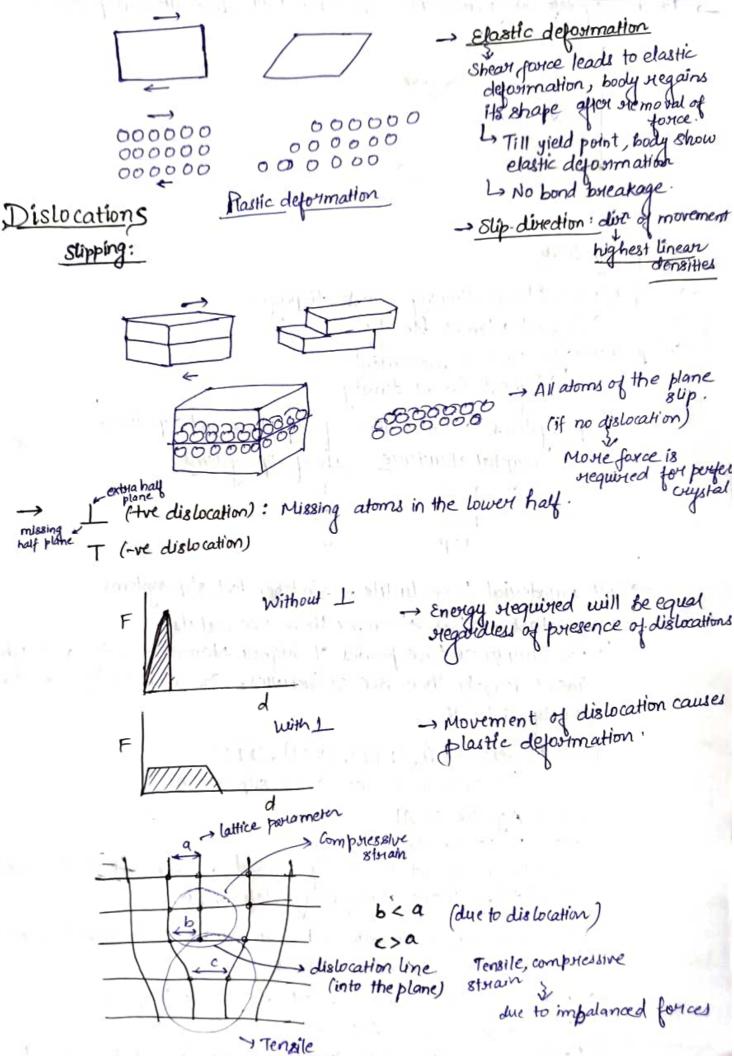
- → Till elastic limit, intermolecular forces of attraction help restore to the original state.
- Normal forces donot contribute in only deformation (only shear forces do).

Plastic deformation: change in the arrangement (e.g., neighbows)
of atoms due to mechanical forces.

- During this, bond breakage happens and then bonding takes place.

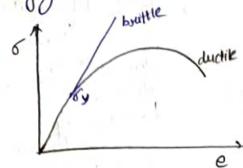
-> slip plane: Plane along which slip is favourable.

highest Lo 1 whole plane of atoms shift. So, the bonds broken will have strongthe planar equal to 1 bond energy x no of atoms in a plane, which is high in



8 Hain

choosing -> For changing deforming material, malerial with dislocation is preferred.



<u>Olip System</u>

-> Slip plane: Plane allowing easiest slippage.

highest planar density Slip direction: Jun of movement highest linear density

Slip systems - combination of slip plane and slip direction.

No of slip systems Crystal structure 48 all a distance of all and BCC HCP

→ for a material to be ductile - 5 independent slip systems.

-> FCC metals we less stronger than BCC metals

La FCC structures have plandes of higher planar density and higher linear density than BCC structures. So, smaller force on easily disboate.

Fcc: planes: (111), (1 [1), (1 11), (111) → 4 planes, 3 sides > 12 slip systems

FCC -> Ag, Au, Cu, Al BCC - Fe, W, CH, Mo.

- slip planes are not so closely packed as compared to For metals-Need high shear strength for deformation.
- -> FCC metals have relatively lower ductile to builtle transition temperature than BCC naetals.
- Dislocations can easily wander at higher temp, as atoms have thermal energy to dislocate. La At sub-zero temps, dislocations are more difficult, in addition to lower

thermal energy.

7	
	- BCC structures will have longer distances to shift, making shifting
30	difficult > sharper transition temp and lower ductility.
30	Slip plane in Applied force; Minm 8thess to cause yielding, $\phi = \lambda = 45^{\circ}$ normal Course sectional Tors, = ofor $\lambda = \phi = 80^{\circ}$ (No 8lip, no fracture) area = A T = From to cook on 2)
3	A A
3	distr Cuitically He solved yield point
	Tensile axis Schimid factor
	- Metals with dislocations have lower strength.
	(Dislocations move plastically on mechanical loading.
	Designing requires higher strength.
5	Manufacturing requires lower strength.
	-> By heat treatment, we can after the internal structure, not the
5	shape of material.
9	Used to increase / decrease the strength (hard/soft).
2	- Dislocations can't move from one grain to the other.
•	get piled up at the quain boundaries.
-	1111 forms
5	
	Loundary
-	-In the vicinity of a creak, a series of dislocations are always found.
	Characteristics: Structure - More quain boundarie
•	mand strength.
A	Performance Properties
750 750	
70	-> Otructure sensitive properties: Hardness, Yield strength, tensile strength, ductility, fatigue, creep, electrical of thermal properties
700	Strength, ductility, fatigue, creep, electrical of thermal properties Structure insensitive properties: Young's Modulus, Melting points. Specific heat Depositive order Nills in the Melting points.
730	1 The state of the
13	-> Physical properties: Density, Thormal, Magnetic, Optical, Electrical
7 30 7 30	-> Physical properties: Donsity, Thormal, Magnetic, Optical, Electrical -> Mechanical properties: Striength, Ductility, Hordness, Impact strongth, Fatigue, Greep, Wear.
2	14-11-11-11-11-11-11-11-11-11-11-11-11-1

Handness Li Resistance to lacalised plastic deformation. - Grain structure is not uniform after casting structural applications don't use Outermost: Finer grains' the products of casting b/c it Middle: Columnar grains I has non-uniformity contre: Bigger goldins Footmed poloducts are used → Super alloy: 8-10 components → dendritic structure b/c of higher no of components. welded component has bigger quair size. -> Some yesistance (Borne metals having atomic imputities) to movement of dislocations can increase strength. - Twee metals have higher ductility but lower storength, hence can be easily deforthed. -> Perfect lattice: no plastic deformation, no ductility, no toughness, very high strength. → Gream boundaries: 2D defects. Most of the metals are poly-crystalline.

- Gas twibine metals one orgstalline (not polycrystalline) for

- Presence of vacancies decrease the free energy of system, hence

Righer temperature applications.

The March of the

they are thermodynamically bound to occur.

SOLID SOLUTIONS Imperfections: Vacancies, Impurity Interstitial Substitutional impusity imposity AL-FCC fe is an Local tensile styess compressive distostion Strew field (for local size of impurity) Size of interestitial atom'> size of void → G, B, N, O, H → occupy voids (DO NOT SUBSTITUTE) - Mixtures: Two or more substances which are not chemically united -> Solution: Substances which are physically inseparable and are chemically united together. -> Alloys are solid () solution. -> Addition of foreign element should not change the crystal structure of base metal. 4 In interstitial sites: Interstitial solid soln (Substituting lattice points: Substitutional solid som -> Strength & Ductility all why does dudility decreases on alloying? Thase: Thysically distinct and chemically homogeneous position of a system with particular chemical composition. -> Ouzn: Intermetallic Compound (defined Storchiometry) 4 NigAL, TigAL, CuAle Cuin super lattice: has a different boundary p regular arrangement Rest of the part of Qu-Zn: Substitutional solid soln

Bruss: Zn is added to Cu (Zn: HcP, Cu: FCC) ((FCG) 1 Substitution solidsoln
foreign/alloying host Substitution solid soln element
element
-> Steel: Interstitial solid soli of Cm re.
For larger size of substituting atom, it towards towards the tensile stress field below dislocation line by diffusion in liquid state (when alloy is being produced).
and start and to be a first and the start an
-30MPa +30MPa +10MPa L
+30 MPa +10 MPa
partially relaxed State
I I I I I dislocation has to move,
even greater force has to be applied.
even geteater force has to be applied. -30 MPa +30 MPa
-20Ma Extua 8tress field
-> Guades stames use in distante yelutting
in higher strength after substitutional atomis
aaaca.
-> Substitutional atom acts as an anchort in the lattice.
flence, alloys have higher stolength compared to pure metal.
→ If smaller atoms are added, they have tensile stress field and get attracted to compressive stress field.
- Interstitial atoms generate compressive stress field, so
those atoms get attracted towarids tensile stress field under
dislocation lines.
the state of the s

Hume-Rothery Lule: For substitutional solid solution

1 Atomic Size, factor:

- of the size difference is less than 8%, then there is a complete solid solubility.

-> Partial solubility: There is a stange in which solubility is

possible.

- For complete solubility: Any quantity of A can dissolve with any quantity of B.

-> The size difference should be less for less lattice distortion

for lower striets field energies.

→ I Dr. 1. ∈ (8%,15%) → partial solubility Mismatch = Produte - Isolvent) × 100%

→ 9 An >15% -> no solubility Eg, a-Ni - complete solubility Cu-Ag -> partial solubility.

-> Alloying increases strength as dislocations can't move easily.

- Interstitial atom will influence the strength more than what we can get in substitutional gold goth

(2) Electrochemical factore:

- of there are metals which are electropositive and the other one is electownegative, then they will form ionic compound reather than and alloy.

B) Crystal Structure:

- for complete solid solubility; The solvent and the solute must have some crystal structule.

Cu-Zn → partial Cu-Ni -> complete 1 Valency: - A metal of lower valency is movie likely to dissolve the metal of higher valency. Both solute and solvent shall have equal valency. g &n m Cu → 38.4% au manelement metal element metal $\frac{e}{a}$ (electron) ratio: $\int_{a}^{e} \left| \frac{1}{a} \right| = \frac{1}{1} = 1$, $\int_{a}^{e} \left| \frac{1}{a} \right| = \frac{2}{1} = 2$ Cu $\geq 2n$ alloy: $\frac{e}{a} \left(\frac{1}{a_1 \cdot 2n} \right) = \frac{3}{2} = 1.5$ alloy → alloy Bn - alloy $e = 2 \rightarrow e = 1.5$ $\frac{e}{a} = 1 \rightarrow \frac{e}{a} = 1.5$ - To promote metal bonding, tree es are needed. When It is added to Cu, In provides more free e-than Cu, hence increasing metallic bonding and favours alloying > Types of Jubstitutional solid solution: Random, Clustweed, Ondered -> For Instrustitial Solid som: - size of solute should be comparable to posse size. - Solute should have comparable electrionegativity as the base

for complete solubility, solvent of solute must have some cuystal

HERMODYNAMICS

First Law: DU=Q-W (sign conventions); dV=8Q-8W

Second Law: DS>0, DS = Qnev, ds = & Qnev.

→ work, dw=P.dv

measure of accomodation h volume → Internal energy, du=T.ds-P.dV

-> Enthalpy, H=U+P.V m> how much volume is going to change. Most metallivigical pricesses are corried out at constant

pressure.

dH=dU+ P.dV + V.dP > dH=8Q-SW+P.dV+V.dP

= 8Q + V.dP=TdS+VdP

dH|p= SQ=T.ds

 $\rightarrow \Delta S_{univ} = \Delta S_{swor.} + \Delta S_{sys.}$

-> For a process at constant temperature and pressure:

 $\Delta S_{8WM} = S G_{8WM} = -S G_{8y8} = -dH_{8y8}$

-> dSuniv. = dSsys. - dHsys.

-Td Suniv = -T.dS sys. +dH

Gibbs Free Energy_

In the component of the total energy of a system that can to work at constant temperature and pressure.

Whe energy in a physical system that can be converted to do

Li Function of internal energy of randomness/disporterness of system. G=H-TS

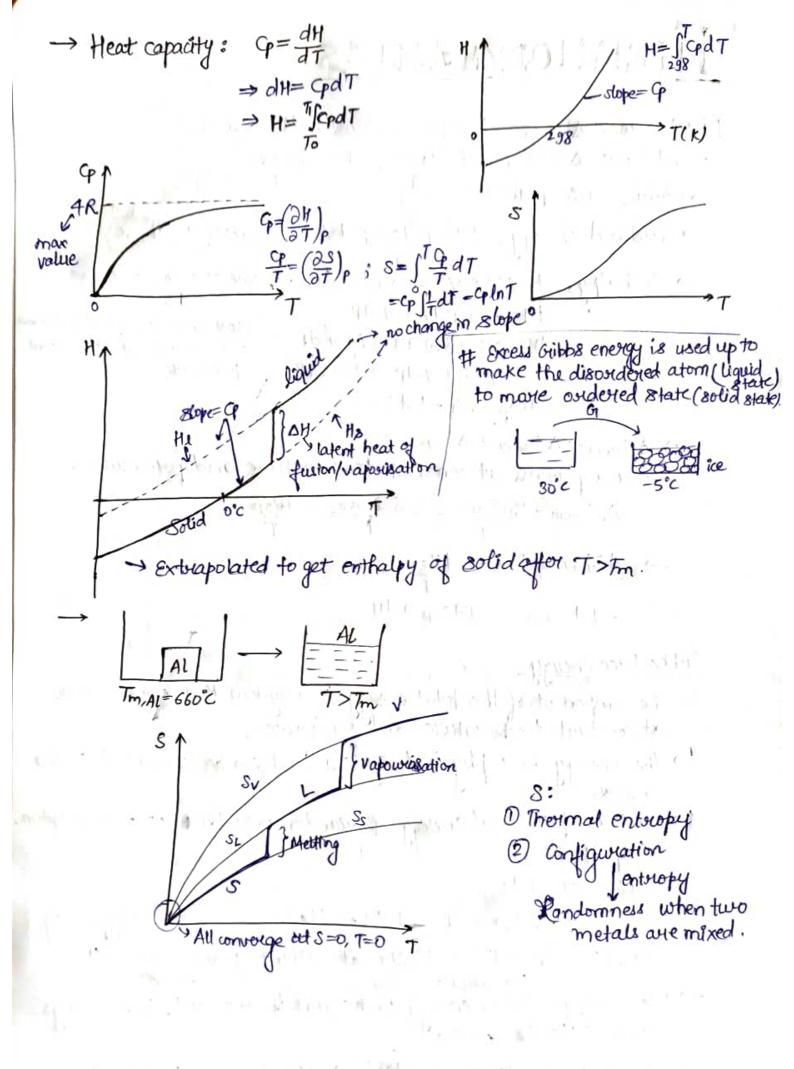
dG=dH-Tds

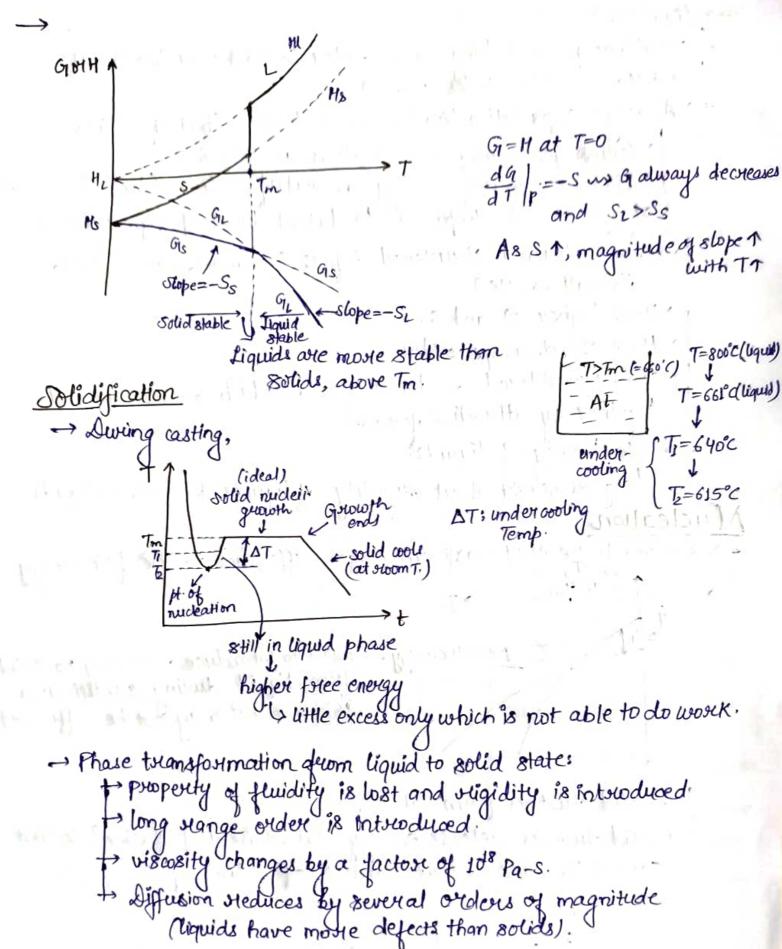
= dv+ p.dv+ v.dp -T.ds - SdT.

⇒ dG= v.dP-S.dT); dG/dT at constant polesswie=-5. La Maxwell's equation

-> Free energy: Extra energy that what is required, that brings changes to the system.

- At any temperature, the stable state is the one that has lowest force-progy.



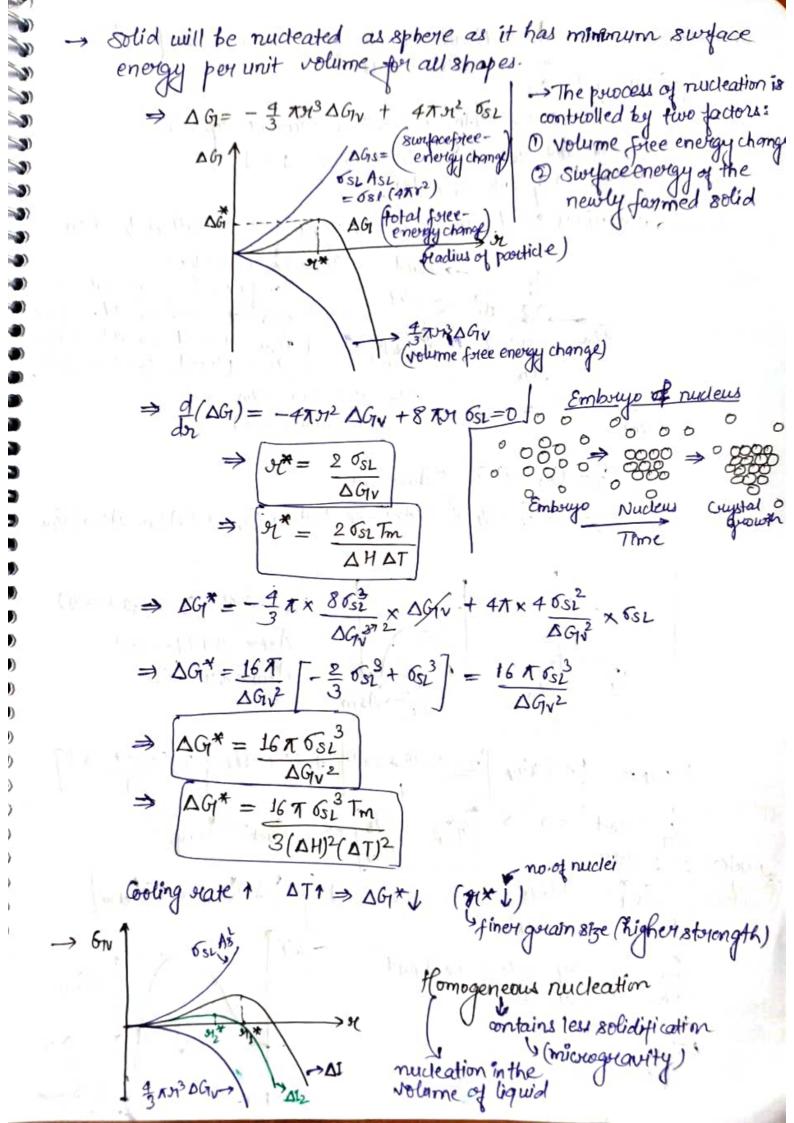


-> Orderliness over distances comparable to interatomic distances is called shout-range order, whereas orderliness repeated over infinitely great distances is called long range order.

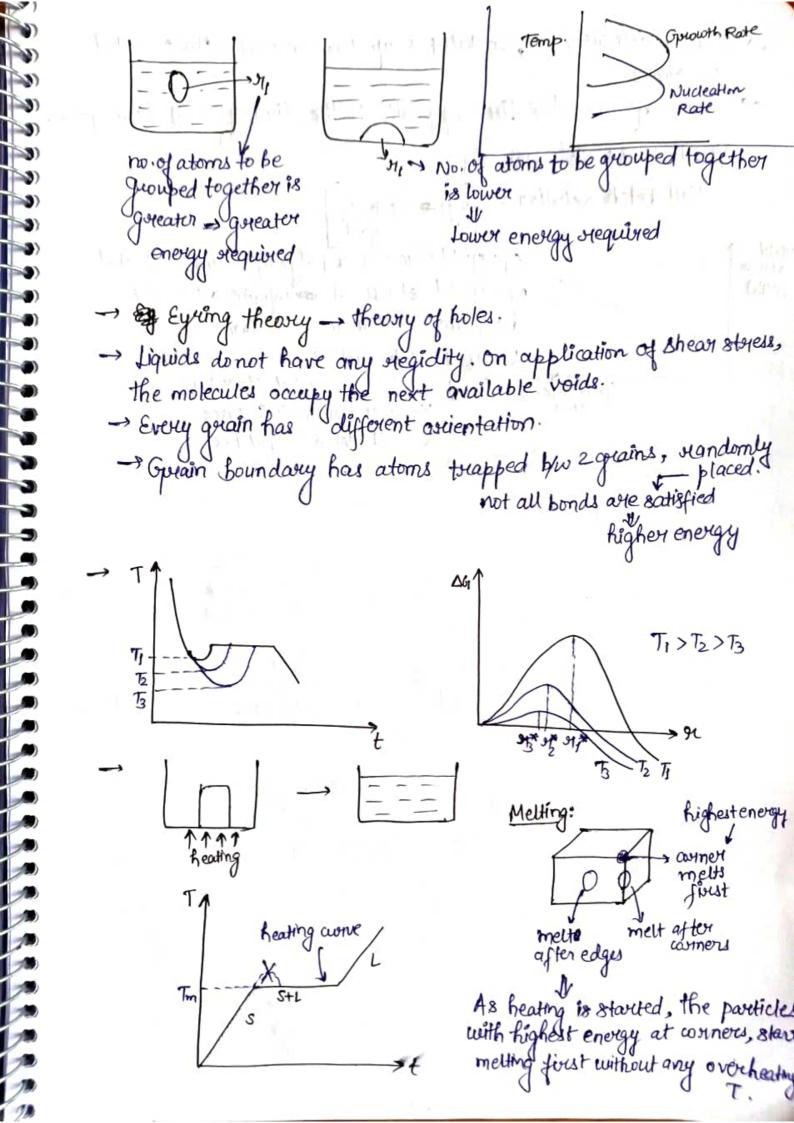
→ <u>Liquids</u>: Neither possess long range order (solids) nor the lack of interaction b/w atoms (gases). + Average separation yw atoms is close to that of solids. Shrinkage during solidification is 2 to 6%. of fusion as compared to latent heat of vaposition. - Have additional structural defects (vacancies, interstitials, dislocations, etc.) → Have higher U and S. Have shout-varge order. to can be considered as dense gas in which atoms are held fogether by attractive forces! +> Hole theory of liquids Ligites insight about sugidity of liquids & voids in liquids. Jucleation -> Duiving force for tolanoformation = Difference in the free energy Dexcess energy wo used to intocoduce ordering to solid from liquid during solidification (this amount may not be sufficient) Ly solid clusters form at T2 Solid clusters release energy (latent heat of fusion), so that causes the suse in temperature often the dip.

A nucleus is essentially a small group of atoms that have taken up avvangement in definite space lattice, is stable and capable of fwither growth. - If the no of nuclei is large, then energy released will be greated than the energy absorbed from the swowndings to form solid dustout Doundary G15 = H5 - T. Ss GL = HL-TSZ (Gs-GL) = (Hs-HL) - T(Ss-SL) ⇒ AG = AH -TAS At Tm, DG=0 DH-TDS=0 $\Rightarrow \Delta S = \Delta H / \Delta H$: heat of fusion, $H_1 \Rightarrow \Delta S = H_2$ we can control grain $\Delta G = H - \frac{H}{T} \times T = H \left(1 - \frac{T}{Tm} \right)$ DT↑ ⇒ DG1 ⇒ more solld $\Rightarrow \Delta G = H_f \left(\frac{T_m - I}{T_m} \right)$ ⇒ QG= HGAT Tm mosse grain boundaries -> The release of heat when a metal solidifies indicates that the coustalline phase has a lower Oribbs Free Energy Gr, than Crystal that will the liquid. Liquid. Mudei <

Guain Boundary: to where grains meet in a solid + townsition region you the neighbouring orystals. High angle grain boundary- Orientation diff. b/w adjacent grains >15 Low angle grain boundary- orientation diff byw adjacent grains <15° At stoom T, grain boundaries have higher strength. → During casting, we make the process faster to introduce more grain boundaries so the dislocations can't move across the grain boundaries. Hence, the material possess higher strength. → Force energy change per unit volume, $G_{L} = \Delta G_{V} = \frac{\Delta H \Delta I}{T_{m}}$ for same volume swiface area volume = 47012 energy > energy lower free energy on the swiface, atoms have dangling bonds. once a solid is formed, there is a swiface energy associated -> Swyace energy Tes energy of system formation of solid les energy of system. swifaceenergy of solid-liquid
swifacearea interface → G1= (V8+VL)G12 Gz = V8 Gv + VLGV + O8L A8L DG = G-G1 = V& GN + VIGIN + OSLASE - VS GN - VLGIN => DG= Vs (GV8-GV) + GSL ASL ⇒ [DG = GSLASL - VS(GIL-GIV)] (DGv=Gv-Gv>0) ⇒ (DG= GSL ASL - VS DGV)



-> Heterogeneous Nudeation: Bubblesof coz in a glass of coke form at the walls. Lieg, artificial siden Luse something which has similar cryptals Structure as ke (h=10km, T=-40°C) 3 & Silver halides s requires solid platform - energy for nucleation I when there is a surface -> liquid swiface energy per unitarea: Tim= of liquid-mould interface 18m = of solid - mould interface 128 = of liquid -solid interface 618 coso + 68m = 61m cos0 = (51m - 58m) Gre (Vs+Ve) Gr + Am. Fin G2= VsGN + V1 GV + ABL 881 + Asm 8sm + (Alm-Asm) Fm $V_8 = 1713 (2-3080 + 6630)$ As1 = 2772 (1-0080) Asm = x228in20 $\Delta G_{net} = -\frac{4}{3}\pi H^{3} G_{V} \left[\frac{2-3\cos\theta+\cos^{3}\theta}{4} + 4\pi H^{2} G_{S} \right] \left[\frac{2-3\cos\theta+\cos^{3}\theta}{4} \right]$ of (AGnet) =0 > 9th= 2618 > Fithet= 9thomo Nucleation barrier, rudeation $\Delta Ghet = \frac{4\pi \delta_{18}^{3}}{3\Delta G_{1}^{2}} \left(2-3\cos\theta+\cos^{3}\theta\right)$ $\Delta G_{homo}^{*} > \Delta G_{hoto}^{*}$ depends on wetting angle of the liquid with mould wall 0: 0°->180 DG het: 0→1 St 0=10, D Gihet = D Gihomo



- → During solidification, metalitakeup trice like structure called dendrites.

 → Grains form in the dist opposite to the dist of heat absorption.
 - Yield stress vs Guan size

Hall Petch Relation:

(5 / ± 5; + k/a

yield strew (MPa)

of: gield stress of a polycrystalline material of: yield stress at an infinite grain size d: grain size (mean-grain diameter)

K: Hall-Petch constant

Ladepends on crystal stoucture

K= 0.71 MN m-1.5 for BCC

K=0.11 MN m-1.5 for FCC

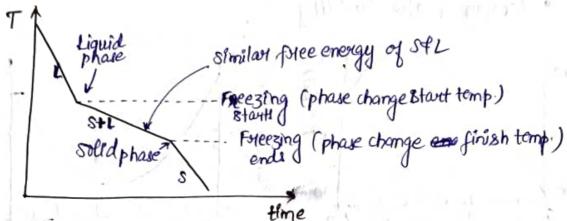
PTICAL MICROSCOPY OF METALS Lowouks on the pounciple of reflection. Stepsin specimen prepation: 1 Rough grunding 1 tolishing with emery paper 3 Diamond / Alumina polishing Antonoville gran ned for it are it as east to the 4 Etching. Etching is controlled chemical deaction - chemical is applied on the swiface, forming coversion products on the swiface. The surface is cleaned soon after chemical is applied so only atoms in grain boundaries react chemicals are choosen such that the coordin products don't stick to Before etching the swya'ce. After etching, sinking is done. Eye piece GB

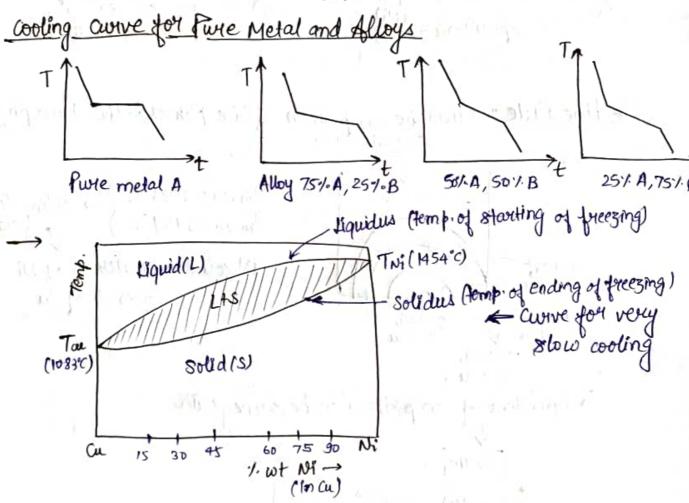
Gran size Weaswichten
1 Intercept Technique:
Lines are drawn in the photomicrograph, and the no. of grain
Boundary intercepts, Ne, along a line is counted.
, , ,
Mean diameter, $\overline{d} = \frac{L}{N_e M}$, L: Length of intercept Ne: No: of great boundary intercepts
M: Magnification
(2) ASTM No: indicates the average diameter of greaters
N=2 ⁿ⁻¹ , N: No. of grains present per square inch under a magnification of 100x
n: ASTM grain size no
-> Fine grains increases the toughness.
the state of the s
Polycrystalline Materials
or grains termed as polycrystalline.
or grains termed as porporprement.
- During the solidification of a polycriptalline solids the constraint sations may start at various nuclei with random
orystallographic orientations.
+ upon solidification, grains of isviegular shapes may form.
The structure will have grain boundaries that could be
seen under a microscope.
$\rightarrow \qquad \qquad$
magnify (") For $n=5$, $N=16 \rightarrow 2n \left(\frac{1}{100} \times \frac{1}{100}\right)$ apparent: $1'' \times 1''$ actual length
I'm under toox
N=160000 grains/inch 2
1 inch =25.4 mm 248 grains/mm2
$\lim_{n \to \infty} \int \frac{\pi x d^2 \times 248}{4} = \lim_{n \to \infty} \frac{2}{n}$
1 tinch tinch 1 hm
1 ch
25.4 = 50 HM

GOOLING CURVE OF AN ALLOY

+ No single melting point for most of the alloys.

Due to continuous change of composition of the solid and liquid phases.





→ Solidus: Max. temp. at which all the components can be in solid state.

Liquidus: Minm temp. at which all the components can be in liquid
state.

→ A boundary b/w a multi-region and liquid solution — Liquidus.

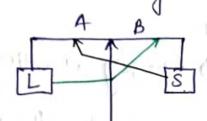
-> Binary alloy: A mixture of 2 metals; constitutes a two-

-> Imosephous system: complete solid solubility of the two components (both in liquid and solid phases) - Alloying to produce a solid solution usually · moreases the tensile strength (TS) · decreases the ductility 300 200 200 (a) 20 composition (w+1.Ni) (Ni) (ai) Composition (wt / Ni) Tie line Rule: Gives the composition of the phases in the two phase negion. 50% Ni, 50% CU Tm, w= 1083°C 7 ist solid: operated % of Ni lower 1. of a 90 y. Ni, 107.Cu 70 y. Ni, 30 y Cu) composition in the same grown Costing liquidus Liquid(L) L+S 71 Tm solid (s) In equilibrium at amposition Y WI, B-

-> After sollidification, heat toteatment is used to obtain homogeneous solids. (Homogenisation treatment)

Concentration gradient is mut nullified.

Lever Rule: Amount of co-existing phases in a two phase region at a given temperature.



$$A \times L = B \times S$$

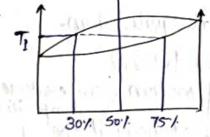
$$\Rightarrow \frac{A}{B} = \frac{S}{L}$$

$$\Rightarrow 1 + \frac{A}{B} = 1 + \frac{S}{L}$$

$$\Rightarrow \frac{B + A}{B} = \frac{L + S}{L}$$

$$\Rightarrow \frac{B+A}{B} = \frac{L+L}{L}$$

$$\Rightarrow \frac{B}{A+B} = WL$$

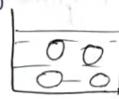


$$W_1 = \frac{c_5 - c_0}{c_8 - c_1}$$
, $W_8 = \frac{c_0 - c_1}{c_8 - c_1}$
where, W_2/W_3 : weight fraction of $L/3$
 $W_1 + W_3 = 1$
 c_8/c_1 : composition of $8/L$
 c_1 : overall composition of alloy
 c_2 : c_3 : c_4 : c_4 : c_6 :

$$W_{S} = \frac{20}{20 + 25} = \frac{9}{9}$$

$$W_{L} = \frac{25}{20 + 25} = \frac{5}{9}$$

-> Lever sure and the line are applicable for binary, homogeneous system.



$$W_1 + W_3 = 1$$

$$\frac{L}{l+\Delta} = W_1, \frac{8}{8+l} = W_3$$

$$W_1 C_1 + W_8 C_1 = C_0$$

$$W_{2}(C_{1}) + (1-W_{1})(C_{3}) = G$$

$$\Rightarrow W_{1}(C_{1}-C_{3}) = G - C_{3}$$

$$\Rightarrow W_{2} = \frac{G - G_{3}}{G - G_{3}}, W_{3} = \frac{G - G_{3}}{G - G_{3}}$$

$$W_{4} = \frac{G - G_{3}}{G - G_{4}}$$

$$W_{5} = \frac{G - G_{4}}{G - G_{4}}$$

Thase Diagram +> Graphical representation of the combinations of temperature and composition for which specific phases exist in equilibrium. +> For a given temperature & composition, we can use phase diagram to detormine 1) the equilibrium phases that are present 1 compositions of the phases. (9) the relative practions of the phases. 1 to predict temperature at which freezing or melting, beings Begins of ends (5) to predict the safe temp. for forming operations/heat treatment. + Phase diagrams provide valuable information about melting, casting, cuystallisation and other phenomenon. thase Rule -> Phase diagrams and phase equilibria are subject to the laws of thermodynamics. + Glibbs phase rule is a criterion that determines how many phases can coexist within a system at equilibrium.

P+F=C+1, P: No. of phases present

F: dequees of freedom (temperature, amposition)

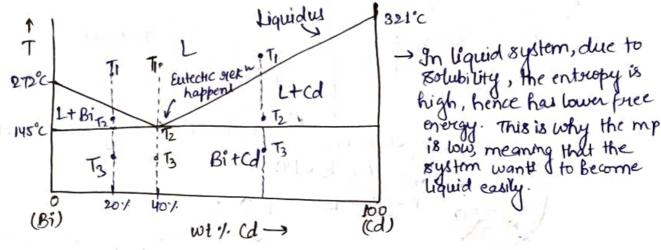
C: components or chemical species

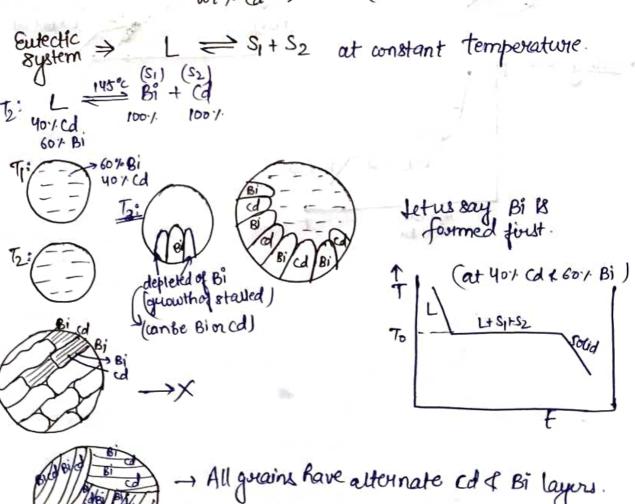
A phase is a physically distinct, chemically homogeneous and mechanically separable region of a system.

EUTECTIC SYSTEM

Late (no solubility at all).

The freezing starts, but 2 phases are obtained as both solid are immiscible in each other.





* 100% eutectic sys

